信頼性試験成績書

0.65um Process Technology Product and Package

Legacy Fujitsu Reliability Engineering Test Report

Wafer Process : Aizu Fujitsu
Assembly : J-Devices

Reliability Test 1

Device Type : MCU 1
Package Type : Plastic LQFP-120 Package

Test Item	Test Condition	Tested Number		Tested Time	Failed Number
High Temperature Operation Life 高温連続動作試験	**150 ℃ V_{DD}=Maximum Rating**	**55**	**(a)**	**1000h**	**0**
Temperature Humidity Bias 高湿連続動作試験	**85 ℃ / 85% RH V_{DD}=Maximum Rating**	**25**	**(a)**	**1000h**	**0**
Low Temperature Operation Life 低温連続動作試験	**-55 ℃ V_{DD}=Maximum Rating**	**25**	**(a)**	**1000h**	**0**
High Temperature Storage 高温保存試験	**150 ℃**	**25**	**(a)**	**1000h**	**0**
Temperature Cycling 温度サイクル	**-65℃～150℃**	**55**	**(a)**	**200cyc**	**0**
Pressure Cooker Test	**121℃, 100%RH: 2.03E5 Pa**	**55**	**(a)**	**168h**	**0**
Pressure Cooker Test with Bias	**121℃, 100%RH: 2.03E5 Pa V_{DD}=Maximum Rating**	**25**	**(a)**	**96h**	**0**

(a) Pre-condition: Baking (125℃, 24h) +Moisture Absorption (85℃/85%RH, 24h) +IR 245℃ Max.

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**	5769404	KUMI	Initial release.